

DP-309847 (DEL01 P-448)

THERMALLY ENHANCED ELECTRONIC MODULE

Abstract of the Disclosure

A thermally enhanced electronic module includes a thermally conductive case, a self-aligning thermally conductive heat sink and a die. The case includes a pivot area with a first shape formed into the case for receiving a first portion of the heat sink and a first portion of the heat sink has a second shape that is complementary to the first shape. The die includes a first surface and a second surface opposite the first surface. The die is mounted to a substrate with the first surface of the die facing the substrate and the second surface of the die is in thermal contact with the heat sink.